# LNJ810L6SRA

Surface Mounting Chip LED

#### SV (Side View) -Case Type

#### Absolute Maximum Ratings $T_a = 25^{\circ}C$

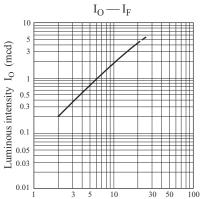
Parameter	Symbol	Rating	Unit	
Power dissipation	P <sub>D</sub>	60	mW	
Forward current	I <sub>F</sub>	20	mA	
Pulse forward current *	I <sub>FP</sub>	60	mA	
Reverse voltage	V <sub>R</sub>	3	V	
Operating ambient temperature	T <sub>opr</sub>	-25 to +80	°C	
Storage temperature	T <sub>stg</sub>	-30 to +85	°C	

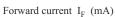
Lighting Color

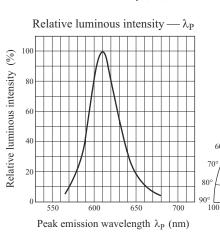
Note) \*: The condition of I<sub>FP</sub> is duty 10%, Pulse width 1 msec.

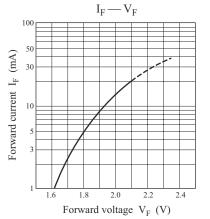
#### Electro-Optical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity	I <sub>O</sub>	$I_{\rm F} = 10  {\rm mA}$	0.6	1.8		mcd
Reverse current	I <sub>R</sub>	$V_R = 3 V$			10	μΑ
Forward voltage	V <sub>F</sub>	$I_{\rm F} = 10 \ {\rm mA}$		1.93	2.6	V
Peak emission wavelength	$\lambda_{\rm P}$	$I_{\rm F} = 10 \text{ mA}$		610		nm
Spectral half band width	Δλ	$I_{\rm F} = 10 \text{ mA}$		40		nm









Directive characteristics

0

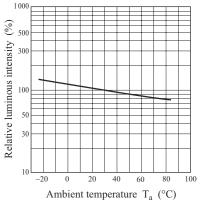
3(

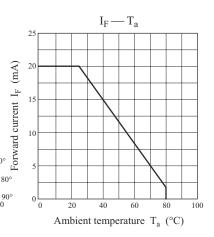
40 5(

60

80







Relative luminous intensity (%)

100

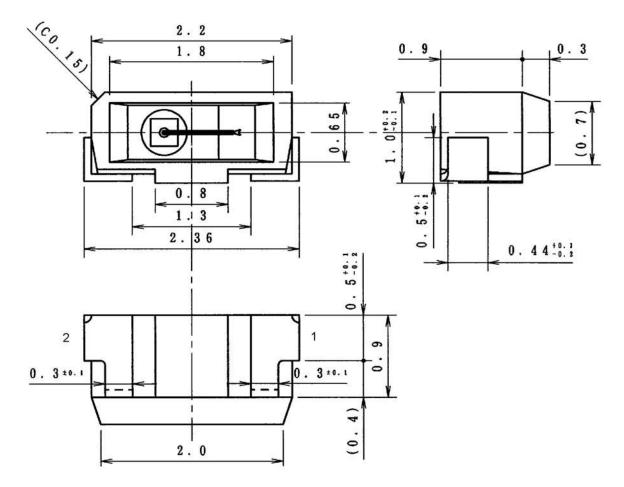
60

<sup>•</sup> Soft Orange

#### LNJ810L6SRA

Package (Unit: mm)

### LLDFSR2J1000



• Pin name

1: Anode

2: Cathode

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